INSTALLING PARQUET AND FLOORING ON CHIPBOARDS (UG 17)

WHAT ARE CHIPBOARDS?

Chipboards are commonly used since their invention in the 1950s and recently in competition with OSB panels and plywood. The research on chipboards happened mainly in the 1920s and the manufacturing hardly changed up to now. Chipboards are produced in different types mainly for construction and decoration.

- ✔ Used as an installation panel, it is ground on both sides.
- ✔ Manufacturing chipboards, wood strands are used. The small size of the wood strands leads to a higher consumption of binder than with OSB panels.
- ✔ Chipboards were invented to increase the usage of wood to a higher percentage. With the chipboards brought to the market, the usage of a tree has been increased from about 50% to 80% and therefore helps strongly to increase the sustainability of the raw material wood.
- ✔ Due to particle size the surface structure smoother than the surface of i.e. OSB panel, which leads to a smaller consumption of adhesive.
- ✔ In EN 312 chipboards are subdivided into classes P1 to P7. For installation only the classes P4 to P7 can be used. Chipboards, are usually delivered with 5-13% moisture content and a longer acclimatization on site can be a good idea.
- ✔ Recently also the emissions of chipboards have been classified by the labels E1 and E2. Only chipboards with label E1 are allowed for interior use.

Class	Sector	Load-bearing	Highly stressable
P4	Dry	✔	
P5	Humid	✔	
P6	Dry	✔	✔
P7	Humid	✔	✔

NOTE WHEN LAYING CHIPBOARDS:

- ✔ Chipboards in the form of installation panels are produced in (conventional) thicknesses of 16, 19 and 25 mm. To accommodate parquet, it is recommended that the chipboards are fully bonded or firmly screwed together.
- ✔ For floating installation (prefab screed), two panels of at least 19 mm thick should be glued and screwed together at right angles to each other. The overall thickness should be1.5 times, better 2 times the thickness of the massive parquet.
- ✔ Gluing of the boards in tongue and groove is done with cold glue of D3 quality, i.g. STAUF Cold glue L. If the boards are glued fully, i.e. to the screed, no gluing in tongue and groove is necessary.
- ✔ Chipboards have to be installed with 2-3 mm distance to walls per meter room length, but with minimum 10-15 mm distance.
- ✔ A proper ventilation has to be installed while working with floating installations, i.g. with special skirtings. Otherwise the system can be damaged by moisture.
- ✔ The boards are screwed on sleepers with a distance of 20-30 cm. Distance and thickness of the sleepers have to be planned by a qualified architect and/or a building planner.
- ✔ In floating installation of Chipboards, and when bonding them to wood types (e.g. maple, beech) and/or to parquet dimensions (e.g. 10 mm solid parquet, 22 mm strip parquet or solid planks) which are sensitive to swelling pressure, it should be noted that if high swelling pressure (e.g. high humidity) occurs, strong tension can build up on the parquet surface which can result in the floor construction welling up.

Flooring	Installation	layer / thickness
Elastic flooring	Screwed on sleepers	single, 25 mm
	Floating	single, 25 mm
Parquet	Screwed on sleepers	double, 16 mm
	Floating	double, 19 mm

INSTALLING FLOORING AND PARQUET ON CHIPBOARDS:

- ✔ Chipboards are generally well suited for resilient and textile floor coverings and parquet. However, the rather coarse surface structure of the installation panels can become apparent when resilient floor coverings are installed. Levelling with a self-levelling compound is usually required.

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- When bonding parquet to Chipboards, slightly increased wood swelling must be expected due to its relatively low absorbency in comparison with bonding to screed.

- A surface covered with OSB constitutes a relatively even and level substrate. The risk of cavities forming during parquet laying is therefore generally much lower than with laying on cement screed, for example.

APPLICABLE PRIMERS FOR LEVELLING COMPOUNDS ON OSB

	STAUF XP 10 [1) 2)] STAUF XP 20 [1) 2)]	STAUF GS [1)]
STAUF VDP 130	✔	
STAUF D 54 [3)]	✔	✔
STAUF VDP 160 [3)]	✔	✔
STAUF VPU 155 S + STAUF Quarzsand	✔	✔
STAUF WEP 180 + STAUF Quarzsand	✔	✔
STAUF VEP 195 + STAUF Quarzsand	✔	✔

1) Add STAUF reinforcement fibres.
2) The maximum thickness of a cement based levelling compound should never exceed 5 mm.
3) Dilute 1:1 with water.

APPLICABLE ADHESIVE SYSTEMS

	STAUF flooring adhesives [1)]	STAUF Dispersion-based wood flooring adhesives	STAUF reactive resin adhesives	Substrate preparation
Textile floorings	✔			Clean the substrate well; depending on its condition and requirements, prime and fill.
Resilient flooring	✔			
Linoleum	✔			
Laminate flooring			✔	
(full-surface bonding)		✔	✔	
Solid wood flooring		✔	✔	
Multi-layer parquet	Bonding in general not possible, please contact us.			

1) As a rule, a levelling compound is recommended for resilient and textile flooring

The information provided above corresponds to the current state of the art. The information is purely indicative and non-binding, since we have no control over the laying process and because the actual laying conditions on site vary. Therefore no claims can be made based on this information. The same is true for the commercial and technical advisory services that are provided without obligation and free of charge. We therefore recommend carrying out sufficient testing of your own in order to determine whether the result is suitable for the intended purpose. 28062022

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